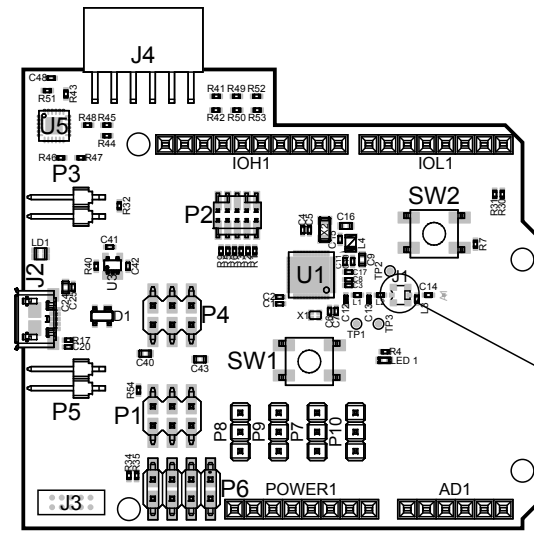
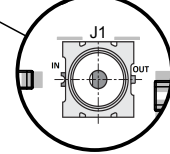


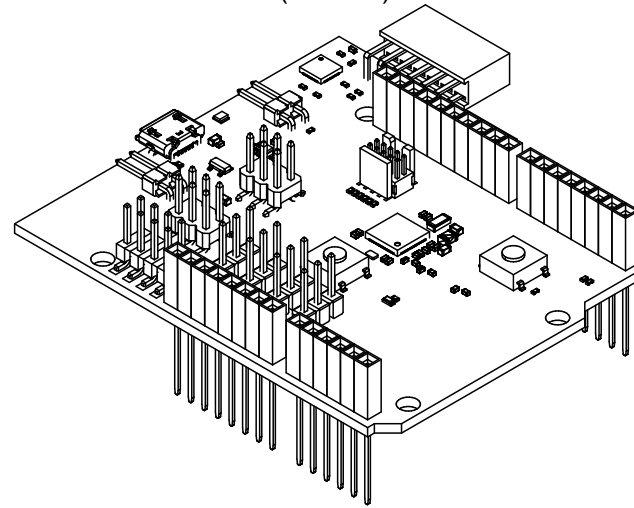
View from Top side (Scale 1:1)



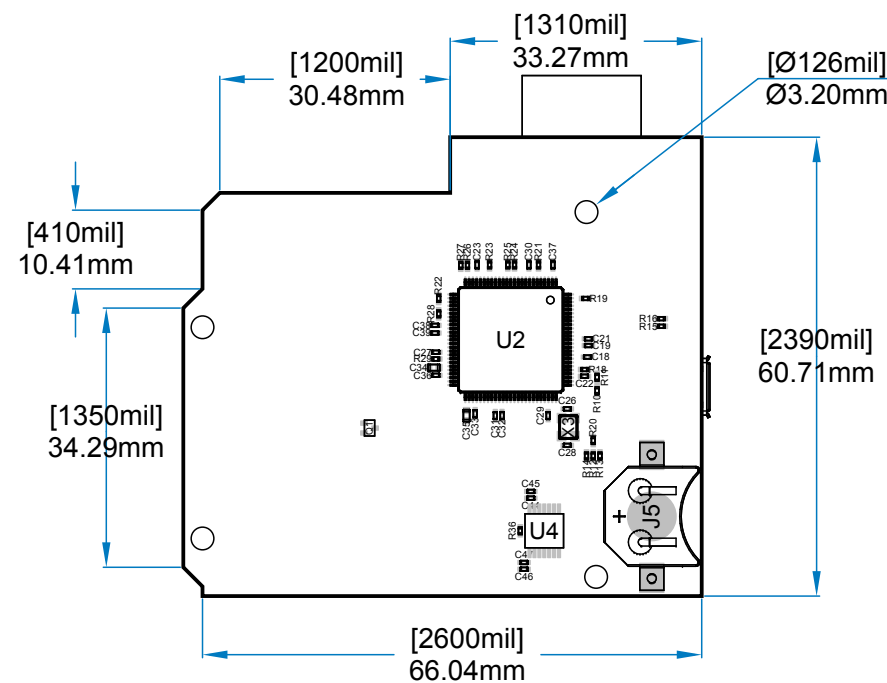
DETAIL A (Scale 4:1)



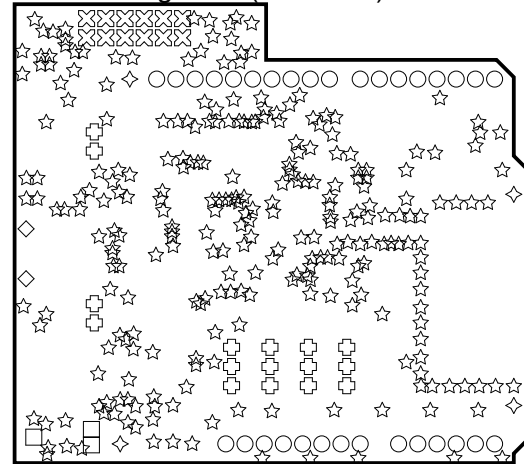
View from Front side (Scale 1)



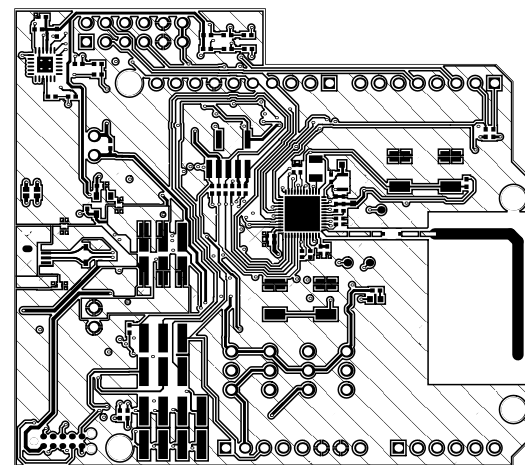
View from Bottom side (Scale 1:1)



Drill Drawing View (Scale 1:1)



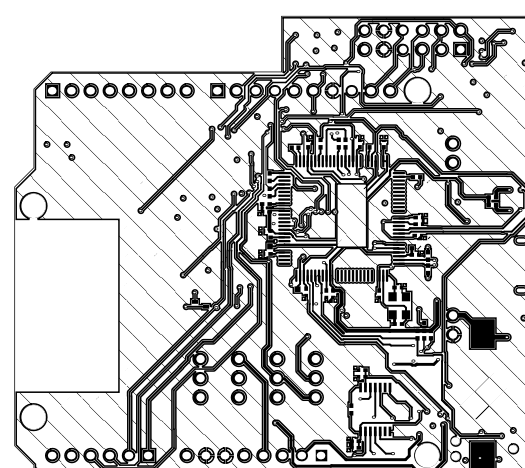
Top Layer (Scale 1:1)



Drill Table

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair
☆	271	8.00mil	Plated	Round	Top Layer - Bottom Layer
◇	2	19.69mil	Plated	Slot	Top Layer - Bottom Layer
□	3	39.00mil	Non-Plated	Round	Top Layer - Bottom Layer
○	32	40.00mil	Plated	Round	Top Layer - Bottom Layer
⊗	12	40.16mil	Plated	Round	Top Layer - Bottom Layer
⊕	16	43.31mil	Plated	Round	Top Layer - Bottom Layer
◇	4	125.98mil	Non-Plated	Round	Top Layer - Bottom Layer
340 Total					

Bottom Layer (Scale 1:1)



Layer Stack Legend

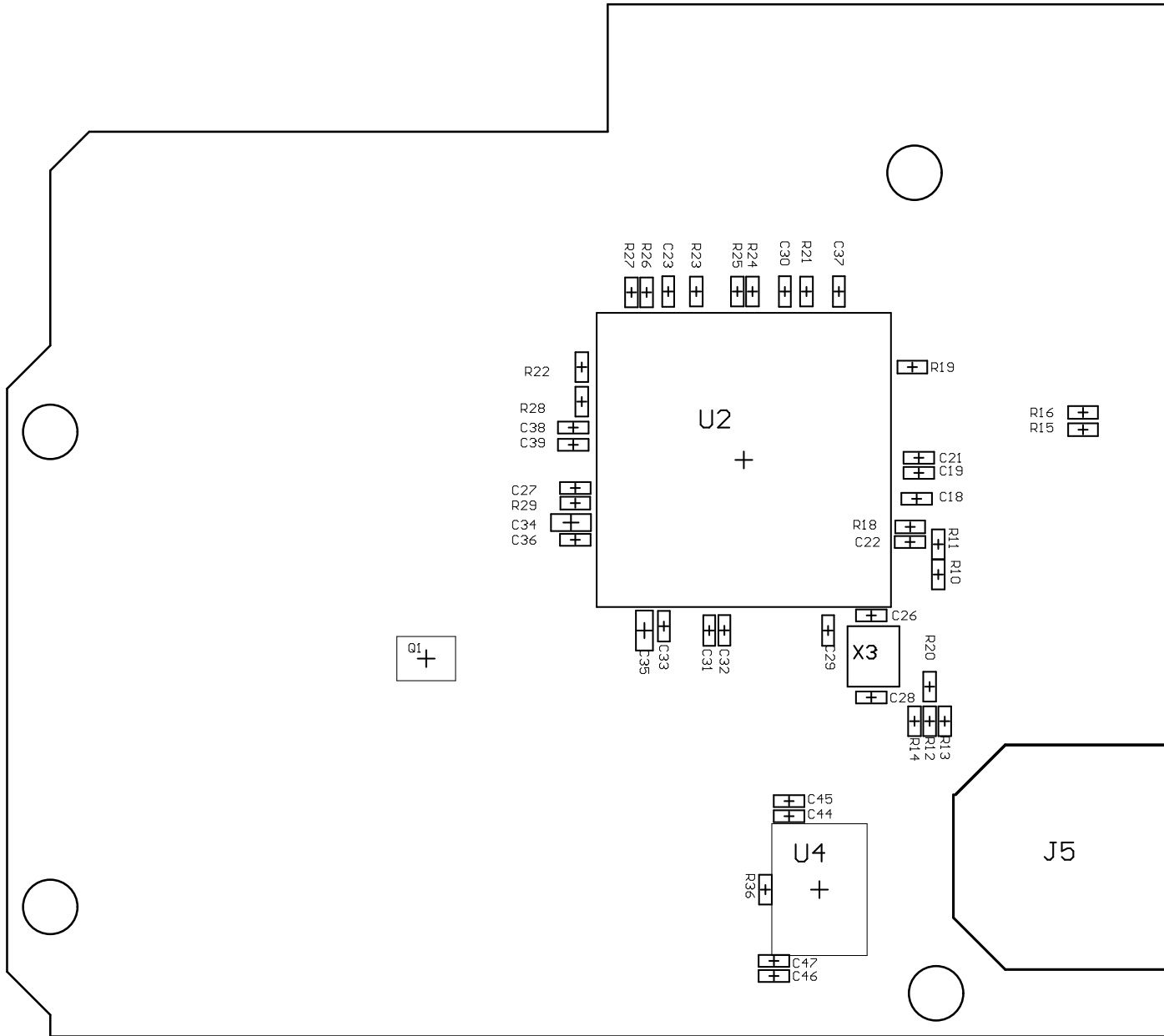
Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Paste			Paste Mask	GTP
	Top Overlay			Legend	GTO
	Surface Material			Solder Mask	GTS
	Top Solder	0.50mil	Solder Resist	Signal	GTL
Copper	Top Layer	2.00mil			
Core		15.30mil	FR-4-370HR	Dielectric	
Copper	Signal Layer 1	0.60mil		Signal	G1
Prepreg		24.00mil	FR4-370HR	Dielectric	
Copper	Signal Layer 2	0.60mil		Signal	G2
Core		15.30mil	FR-4-370HR	Dielectric	
Copper	Bottom Layer	2.00mil		Signal	GBL
Surface Material	Bottom Solder	0.50mil	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
	Bottom Paste			Paste Mask	GBP
Total thickness: 60.80mil					

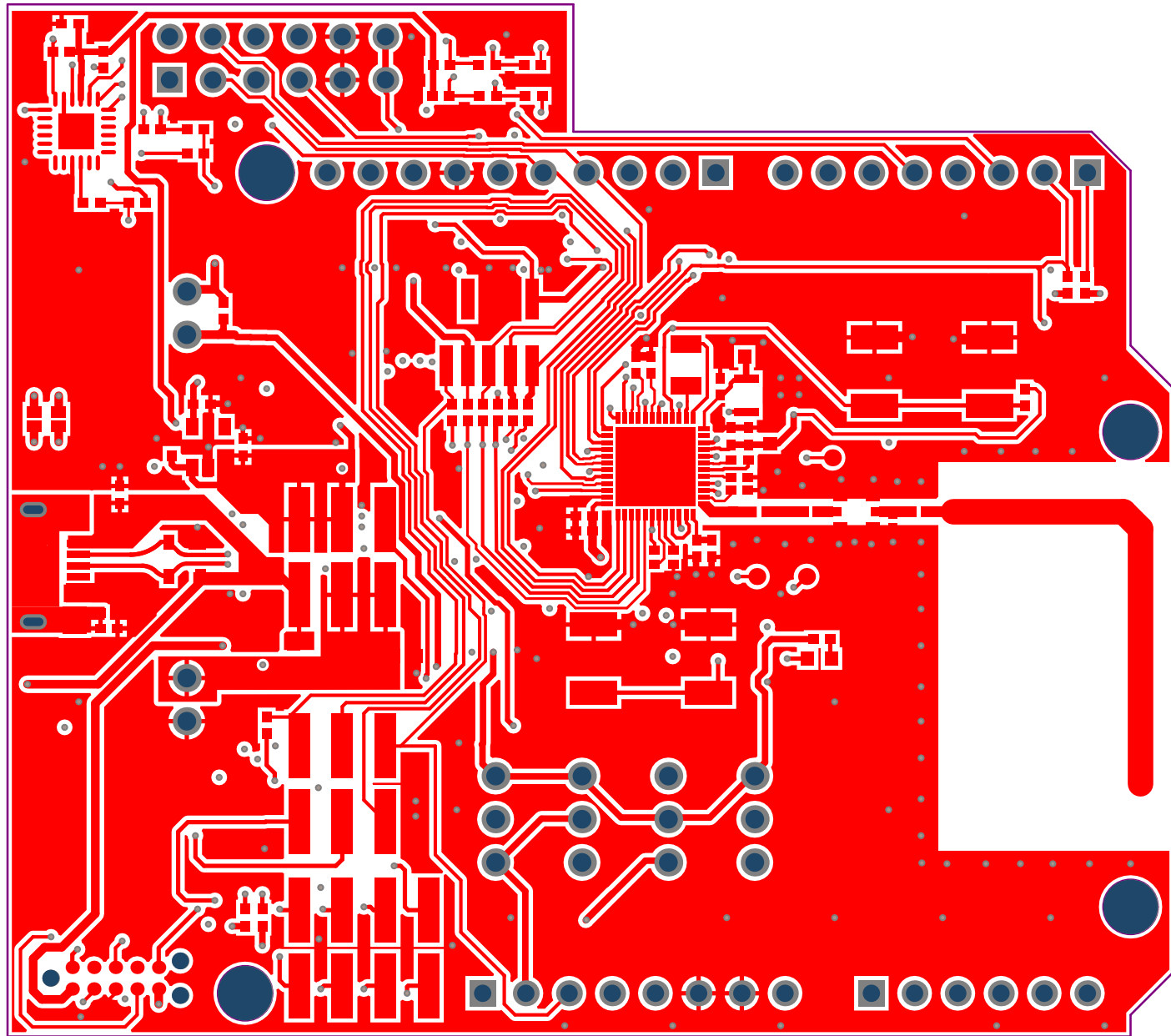
Notes:

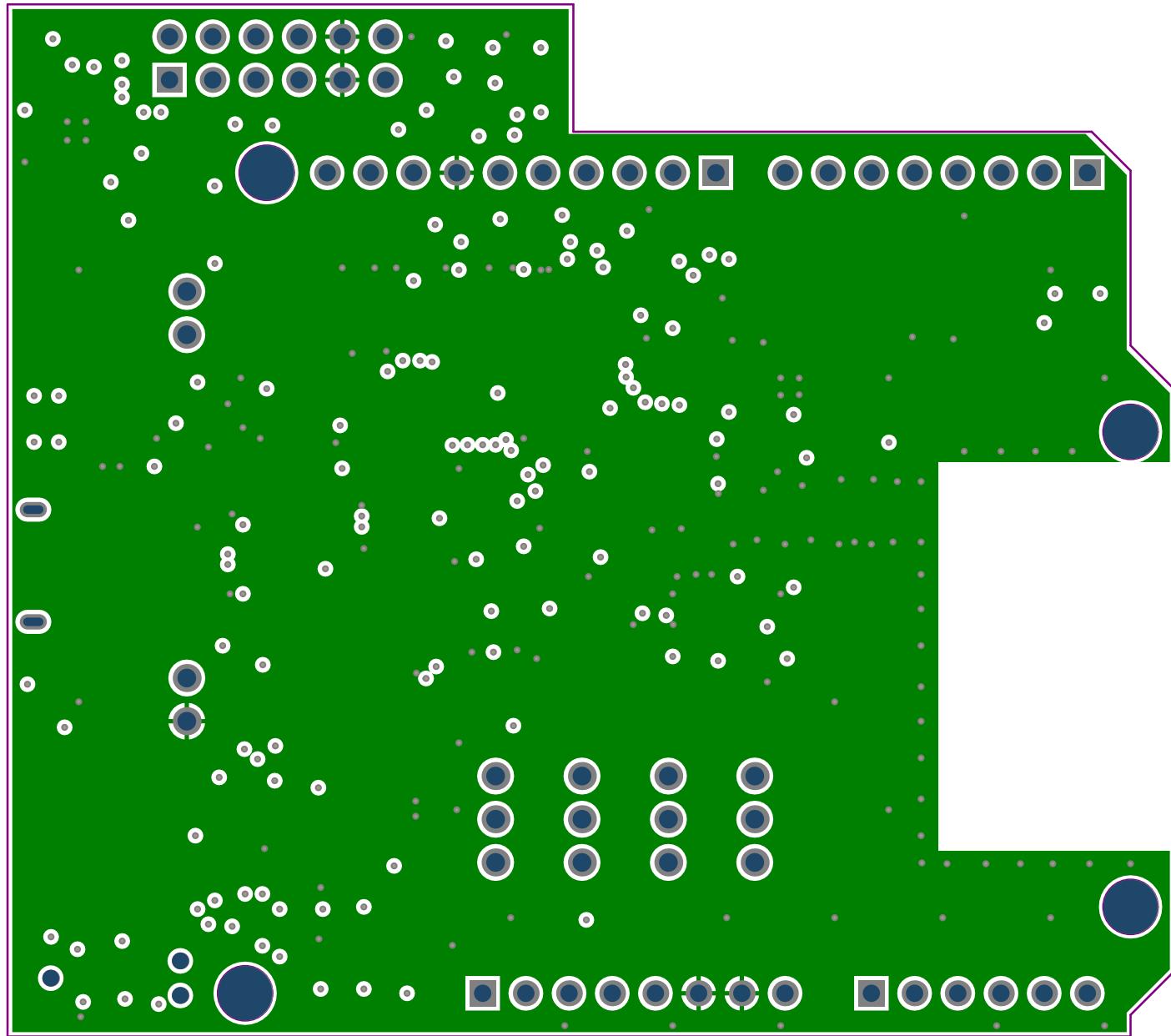
- 1 Fabricate to IPC6012 Class2.
- 2 Board material, Isola 370HR RoHS Compliant with nominal thickness of 0.062 INCH, 1/2 OZ copper on top and bottom layers, 1/2 OZ copper on inner layers.
- 3 Order of layers is Top_Layer, Signal_Layer1, Signal_Layer2, Bottom_Layer.
- 4 All dimensions +/- 5 MIL, unless otherwise specified.
- 5 LDI mask both sides, mask must be between lands. Minimum of 1.5 MIL per side around lands.
- 6 Silkscreen to be white ink, soldermask green. No ink to be on surface mount land pads. Vendor marking on bottom side.
- 7 Board to use ENIG (Electroless Nickel Immersion Gold) finish.
- 8 Board to be 100% tested to Gerber net list file.
- 9 Include a minimum of two fiducias per panel.
- 10 Controlled impedance board: Top_Layer -microstrip,Signal_Layer1-gnd.RF1 microstrip (25mil) traces on top layer shall be 50 ohms +/-10%.
- 11 USB Diff pair controlled impedance to be 90 ohm +/-10%, DHSD_N and DHSD_P traces.
- 12 Minimum copper hole wall plating 1 MIL.
- 13 Maximum warp/twist 0.005 INCH per INCH.
- 14 Finish all conductors +0.000/-0.002 from supplied artwork.

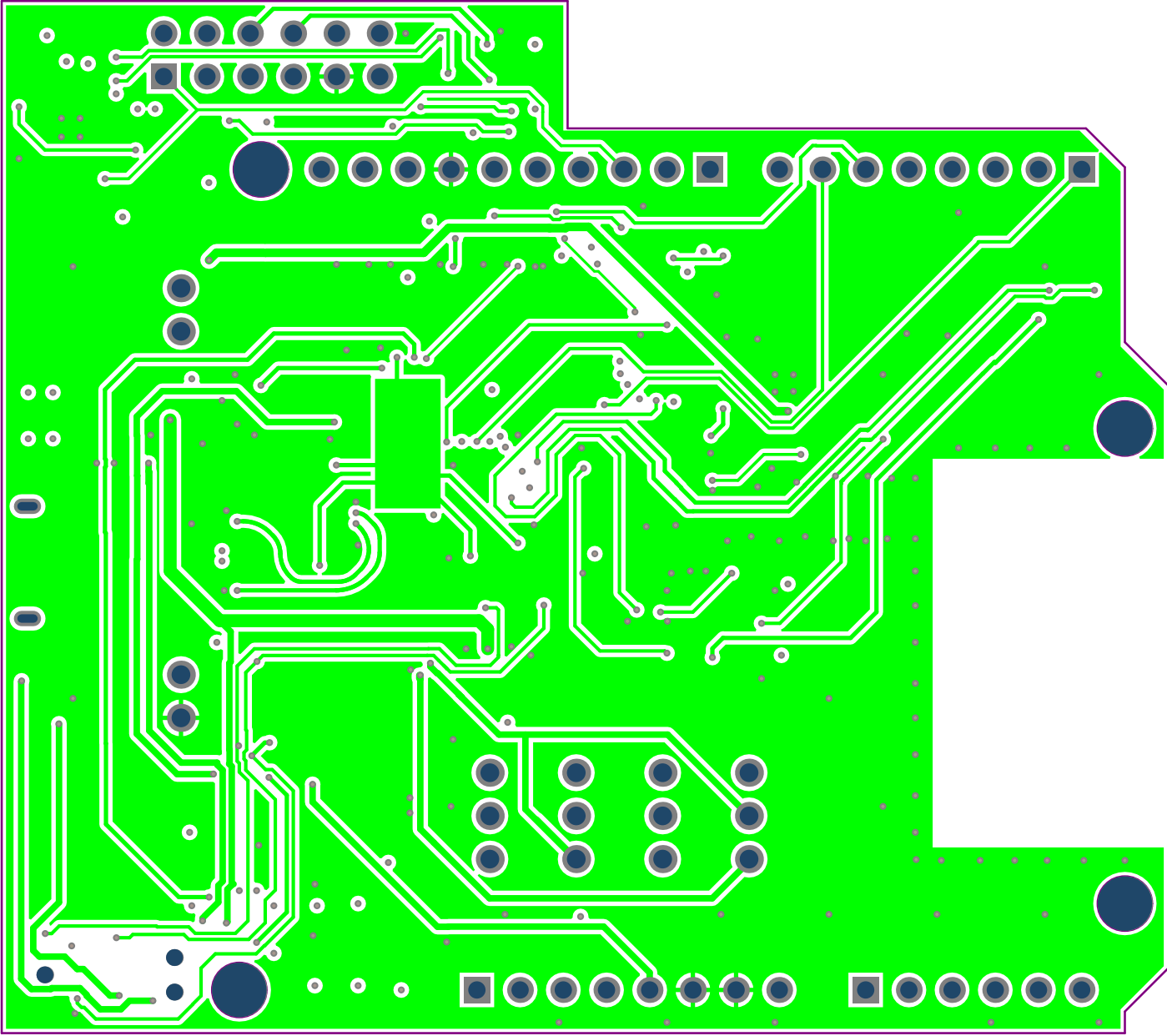
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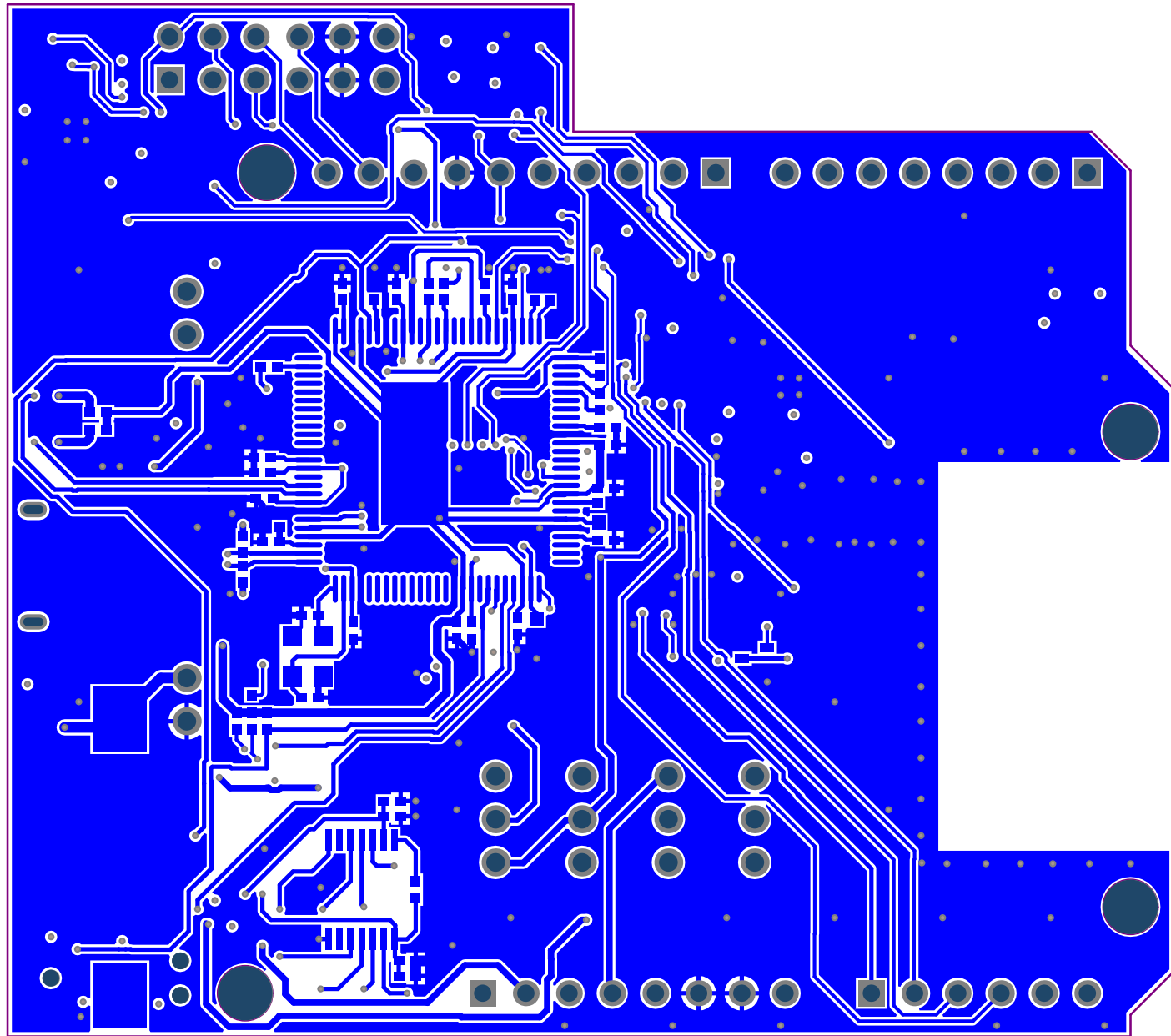
		UNLESS OTHERWISE SPECIFIED:		NAME	DATE	ON SEMICONDUCTOR			
		DIMENSIONS ARE IN INCHES	DRAWN	M.C.	6/22/2017	RSL10 QFN EVB V1.3			
		TOLERANCES:	CHECKED						
		FRACTIONAL±	ENG APPR.						
		ANGULAR: MACH± BEND ±	MFG APPR.						
		TWO PLACE DECIMAL ±							
		THREE PLACE DECIMAL ±	Q.A.			SIZE DWG. NO.			
		INTERPRET GEOMETRIC TOLERANCING PER:	COMMENTS:						
		MATERIAL							
		FINISH							
NEXT ASSY	USED ON	DO NOT SCALE DRAWING				SCALE: 1:1 WEIGHT: SHEET 1 OF 1			
APPLICATION									











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May 2017

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C30
R25
C23
R23

U2

C19

R16
R15

C21
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C18
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C22

C26
C23
C28
R20
R13
R12
R14

J5

C45
C44

U4

R36

C47
C46

C38
C39
R22
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C27
R29
C34
C36

C33
C35
C32
C31

Q1

